

APPENDIX B
VERSION WITH MARKINGS TO SHOW CHANGES MADE
37 C.F.R. § 1.121(b)(iii) AND (c)(ii)

CLAIMS:

1. (Amended) A wire-bonding apparatus for forming electrical connections between a semiconductor chip and a lead frame, comprising:
a plurality of bond-heads; [associated with]
a plurality of work holders, each associated with a respective one of the bond-heads, and configured to support a lead frame in an operative relation to the associated bond-head; and
a controller which is programmable to operate [holding a plurality of leadframes, wherein] each bond-head of the apparatus [is capable of independent bonding operation] independently to perform bonding of wires between a semiconductor chip and a leadframe simultaneously with the other bond-heads but without synchronization of movement [with] between the [other] bond-heads.
5. (Amended) A wire-bonding apparatus according to claim 1, including a storage device [means] in which leadframes are storable and which [are] is operatively connected with the apparatus to automatically provide leadframes to the workholder and/or to automatically receive leadframes that have been processed.
10. (Amended) A wire-bonding apparatus according to claim 1, which includes a cardcage for storing electrical and/or electronic components [for] of the controller and devices [functioning of the apparatus, wherein drivers] to drive mechanical components of the apparatus [are houseable within the cardcage].
14. (Amended) A wire-bonding apparatus according to claim 1, wherein the controller is programmable to operate the plurality of bond-heads to [are capable of] simultaneously [conducting] perform bonding of wires of different types.

15. (Amended) A wire-bonding apparatus according to claim 14, wherein the different types of wires include [bond-heads are capable of conducting bonding with] gold wires and copper wires [simultaneously].

16. (Amended) A wire-bonding apparatus according to claim 14, wherein the different types of wires include [different bond-heads are capable of conducting bonding with] wires of different diameters [simultaneously].

17. (Amended) A wire-bonding apparatus according to claim 1, wherein the controller is programmable to operate different bond-heads [are capable of conducting] to perform bonding [using] according to different patterns simultaneously.